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MMBTA42L, SMMBTA42L, MMBTA43L

High Voltage Transistors NPN Silicon

Features

- S Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Characteristic	Symbol	Value	Unit
Collector – Emitter Voltage MMBTA42, SMMBTA42 MMBTA43	V _{CEO}	300 200	Vdc
Collector – Base Voltage MMBTA42, SMMBTA42 MMBTA43	V _{CBO}	300 200	Vdc
Emitter – Base Voltage MMBTA42, SMMBTA42 MMBTA43	V _{EBO}	6.0 6.0	Vdc
Collector Current – Continuous	Ι _C	500	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) T _A = 25°C Derate above 25°C	P _D	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate (Note 2) T _A = 25°C Derate above 25°C	P _D	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

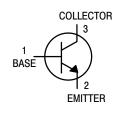
1. $FR-5 = 1.0 \times 0.75 \times 0.062$ in.

2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.



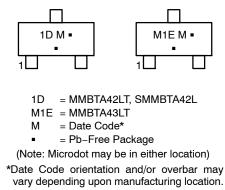
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MARKING DIAGRAMS



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MMBTA42L, SMMBTA42L, MMBTA43L

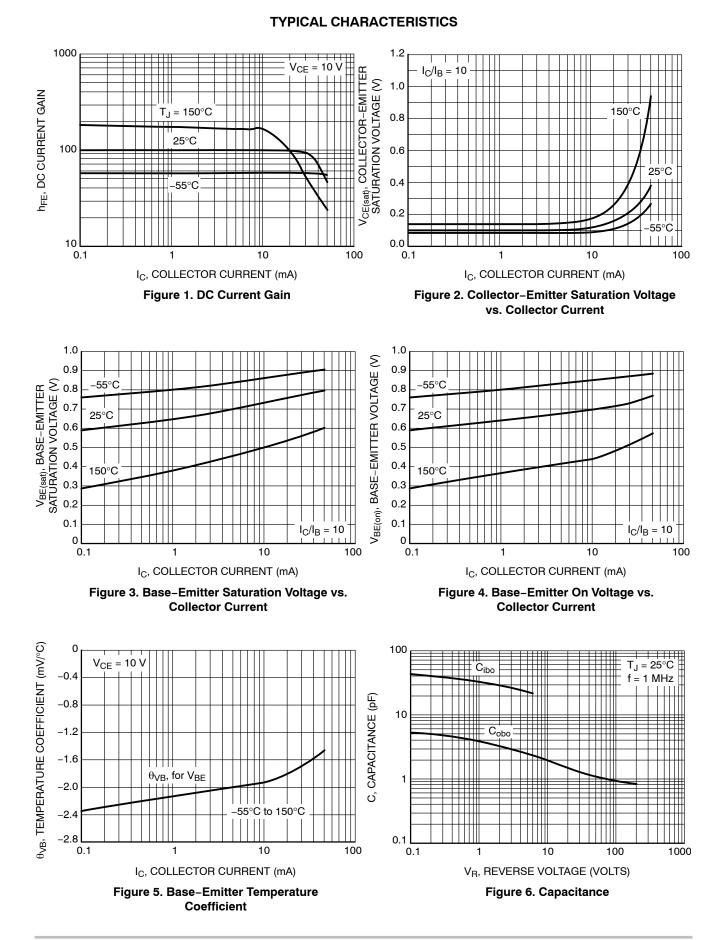
ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 3) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	MMBTA42, SMMBTA42 MMBTA43	V _{(BR)CEO}	300 200		Vdc
Collector – Base Breakdown Voltage (I _C = 100 μ Adc, I _E = 0)	MMBTA42, SMMBTA42 MMBTA43	V _(BR) CBO	300 200		Vdc
Emitter – Base Breakdown Voltage ($I_E = 100 \ \mu Adc, I_C = 0$)		V _{(BR)EBO}	6.0	-	Vdc
		Ісво		0.1 0.1	μAdc
Emitter Cutoff Current $(V_{EB} = 6.0 \text{ Vdc}, I_C = 0)$ $(V_{EB} = 4.0 \text{ Vdc}, I_C = 0)$	MMBTA42, SMMBTA42 MMBTA43	I _{EBO}		0.1 0.1	μAdc
ON CHARACTERISTICS (Note 3)					
DC Current Gain (I _C = 1.0 mAdc, V _{CE} = 10 Vdc) (I _C = 10 mAdc, V _{CE} = 10 Vdc)	Both Types Both Types	h _{FE}	25 40		-
(I _C = 30 mAdc, V_{CE} = 10 Vdc)	MMBTA42, SMMBTA42 MMBTA43		40 40		
Collector – Emitter Saturation Voltage (I _C = 20 mAdc, I _B = 2.0 mAdc) MMBTA42, SMMBTA42 MMBTA43		V _{CE(sat)}		0.5 0.5	Vdc
Base-Emitter Saturation Voltage ($I_C = 20 \text{ mAdc}, I_B = 2.0 \text{ mAdc}$)		V _{BE(sat)}	-	0.9	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product (I _C = 10 mAdc, V _{CE} = 20 Vdc, f = 100 MHz)		f _T	50	-	MHz
Collector-Base Capacitance (V_{CB} = 20 Vdc, I_E = 0, f = 1.0 MHz)	MMBTA42, SMMBTA42 MMBTA43	C _{cb}		3.0 4.0	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

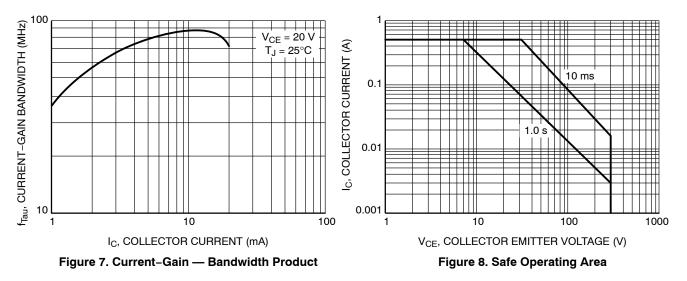
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MMBTA42L, SMMBTA42L, MMBTA43L



MMBTA42L, SMMBTA42L, MMBTA43L

TYPICAL CHARACTERISTICS



ORDERING INFORMATION

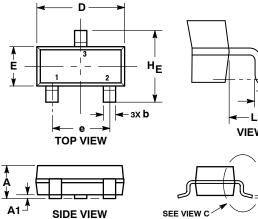
Device Order Number	Package Type	Shipping [†]
MMBTA42LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
SMMBTA42LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBTA42LT3G	SOT-23 (Pb-Free)	10,000 / Tape & Reel
SMMBTA42LT3G	SOT-23 10,000 / Tape & Reel (Pb-Free)	
MMBTA43LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel

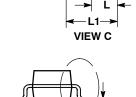
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AR**

0.25







NOTES

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
- MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
- THE BASE MATERIAL.

4.	DINEN	ISIONS D'AND E DO NOT INCLUDE MOLD FLASH,	
	PROTE	RUSIONS, OR GATE BURRS.	

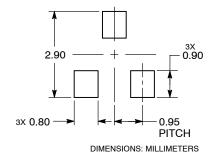
	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.89	1.00	1.11	0.035	0.039	0.044	
A1	0.01	0.06	0.10	0.000	0.002	0.004	
b	0.37	0.44	0.50	0.015	0.017	0.020	
С	0.08	0.14	0.20	0.003	0.006	0.008	
D	2.80	2.90	3.04	0.110	0.114	0.120	
Е	1.20	1.30	1.40	0.047	0.051	0.055	
е	1.78	1.90	2.04	0.070	0.075	0.080	
L	0.30	0.43	0.55	0.012	0.017	0.022	
L1	0.35	0.54	0.69	0.014	0.021	0.027	
ΗE	2.10	2.40	2.64	0.083	0.094	0.104	
Т	0°		10 °	0 °		10 °	

STYLE 6:

PIN 1. BASE 2.

EMITTER 3 COLLECTOR

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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